



Material Content Data Sheet



Sales Product Name		TLS820F0EL V33		Issued		24. August 2015		
MA#		MA001338860						
Package		PG-SSOP-14-5		Weight*		82.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.743	2.10	2.10	21036	21036
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		416	
	non noble metal	iron	7439-89-6	0.689	0.83		8315	
wire	non noble metal	copper	7440-50-8	27.978	33.76	34.64	337643	346478
	non noble metal	copper	7440-50-8	0.086	0.10	0.10	1033	1033
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1207
	plastics	epoxy resin	-	4.600	5.55		55517	
	inorganic material	silicondioxide	60676-86-0	45.302	54.69	60.36	546723	603447
leadfinish	non noble metal	tin	7440-31-5	0.988	1.19	1.19	11927	11927
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9264	9264
glue	plastics	epoxy resin	-	0.141	0.17		1704	
	noble metal	silver	7440-22-4	0.423	0.51	0.68	5111	6815
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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